

高性能脈衝電鍍銅及其在高縱橫比線路上的應用

High Performance PPR Copper Plating for HAR Boards



COPPER GLEAM™ PPR-II Acid Copper

COPPER GLEAM™ PPR-II Acid Copper is specially designed for plating through hole in high aspect ratio boards, working with soluble anodes and simple waveform in vertical application.

COPPER GLEAM™ PPR-II 專門設計應用於高縱橫比之線路板，適用於垂直線可溶性及不溶性陽極，且可透過簡易的波形進行操控。

Features and Benefits 特長及優點

- Perform high throwing power for through hole in high aspect ratio of thick board
於高縱橫比之厚板中，具有高通孔深鍍能力之表現
- With outstanding bath stability and easy to restart after idling
具優越的槽液穩定性及閒置後僅須短時間的預鍍
- Offer excellent thermal reliability
提供優越的熱信賴度

Outstanding throwing power performance 優越的通孔深鍍能力



Aged bath with consistent TP% performance 在老化槽液仍有穩定的深鍍能力

